

ABSTRACT

A film for protective film formation which contains an energy ray-curable compound (B), has the properties described below, and is used for forming a protective film on the back surface of a semiconductor wafer or a semiconductor chip, wherein when a cured product is formed by curing the film for protective film formation by irradiation with energy rays, the cured product has a Young's modulus of at least 500 MPa and an elongation at break of at least 8%.